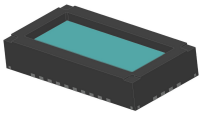
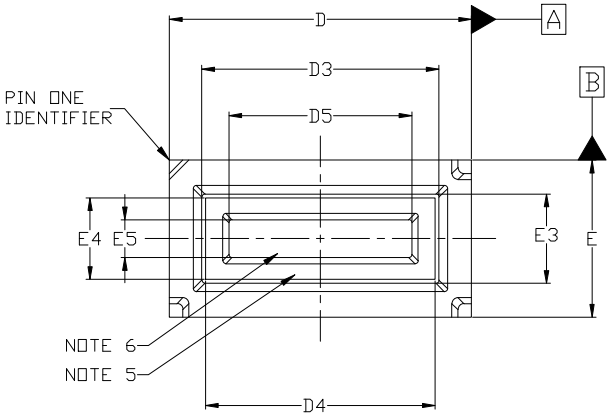
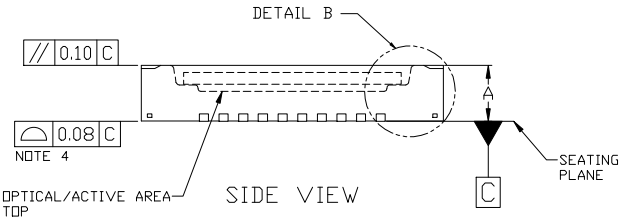


QFN28 10.00x5.20x1.85, 0.65P
CASE 485FZ
ISSUE F

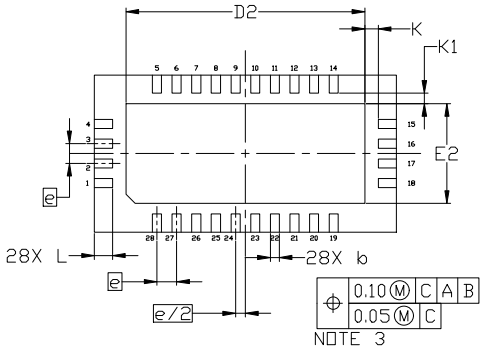
DATE 14 JUL 2023



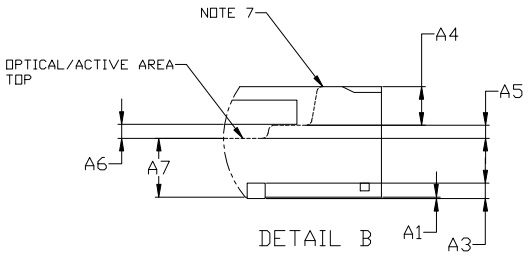
TOP VIEW



SIDE VIEW



BOTTOM VIEW

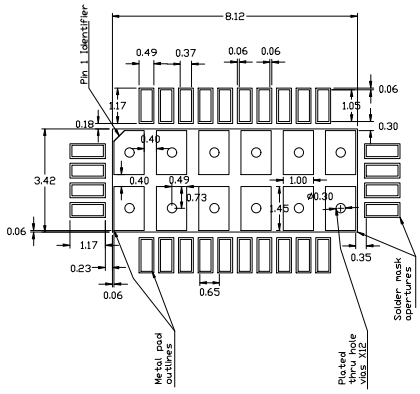


DETAIL B

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. GLASS LID AREA, 0.4mm THICKNESS. DEFINED BY D4 & E4.
6. OPTICAL/ACTIVE AREA IS CENTERED.
   ALIGNMENT TO PACKAGE CENTER: +/- 0.05 mm
   ROTATION ALLOWED: +/- 0.5°
7. MOLD INNER CAVITY RADIUS AT 0.1mm AT 10° DRAFT ANGLE.
8. DIMENSION A6 MEASURES THE BOTTOM OF THE GLASS TO TOP OF DIE.
9. DIMENSION A7 MEASURES THE BOTTOM OF THE PACKAGE TO TOP OF DIE.

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	1.75	1.85	1.95
A1	0.00	---	0.05
A3	0.254 REF		
A4	0.594 REF		
A5	0.256 REF		
A6	0.270 REF		
A7	0.971	1.014	1.052
b	0.25	0.30	0.35
D	9.90	10.00	10.10
D2	7.80	7.90	8.00
D3	7.57 REF		

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
D4	7.32 REF		
D5	6.40 REF		
E	5.10	5.20	5.30
E2	3.20	3.30	3.40
E3	2.67 REF		
E4	2.42 REF		
E5	1.50 REF		
e	0.65 BSC		
K	0.45 REF		
K1	0.35 REF		
L	0.55	0.60	0.65



RECOMMENDED MOUNTING FOOTPRINT*

* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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DESCRIPTION:	**QFN28 10.00x5.20x1.85, 0.65P**		**PAGE 1 OF 1**